

HD74LS241

Octal Buffers / Line Drivers / Line Receivers
(non inverted three-state outputs)

REJ03D0460-0200

Rev.2.00

Feb.18.2005

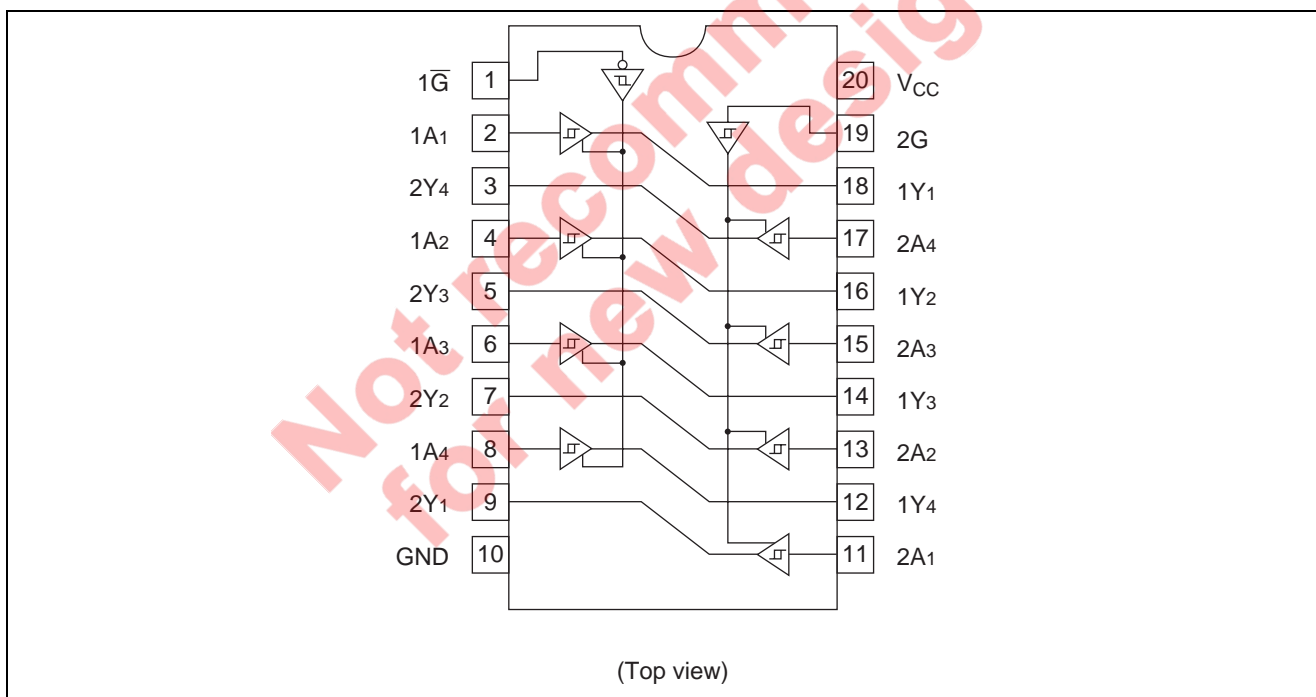
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS241P	DILP-20 pin	PRDP0020AC-B (DP-20NEV)	P	—
HD74LS241FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement

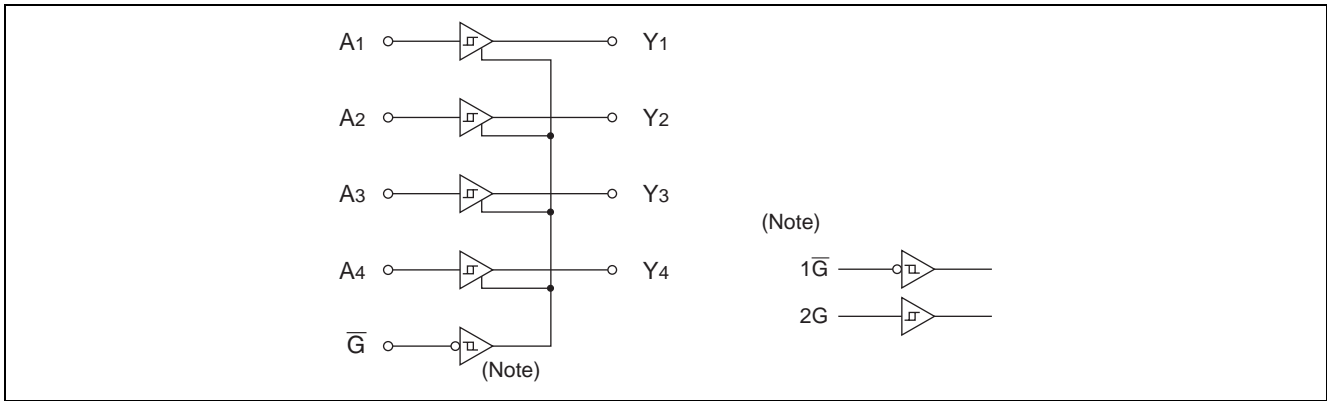


Function Table

Inputs		Output	
$1\bar{G}$	$2\bar{G}$	A	Y
H	L	X	Z
L	H	H	H
L	H	L	L

Note: H; high level, L; low level, X; irrelevant, Z; off (high-impedance) state of a 3-state output

Block Diagram (1/2)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output current	I_{OH}	—	—	-15	mA
	I_{OL}	—	—	24	mA
Operating temperature	T_{opr}	-20	25	75	°C

Electrical Characteristics

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition	
Input voltage	V _{IH}	2.0	—	—	V		
	V _{IL}	—	—	0.8	V		
Hysteresis	V _{T+} - V _{T-}	0.2	0.4	—	V	V _{CC} = 4.75 V	
Output voltage	V _{OH}	2.4	—	—	V	V _{CC} = 4.75 V, V _{IH} = 2 V	
		2.0	—	—			V _{IL} = 0.8 V, I _{OH} = -3 mA
	V _{OL}	—	—	0.4	V	V _{CC} = 4.75 V, V _{IH} = 2 V, V _{IL} = 0.8 V	
		—	—	0.5			I _{OL} = 12 mA
Off-state output current	I _{ozH}	—	—	20	μA	V _O = 2.7 V	
	I _{ozL}	—	—	-20	μA	V _O = 0.4 V	
Input current	I _{IH}	—	—	20	μA	V _{CC} = 5.25 V, V _I = 2.7 V	
	I _{IL}	—	—	-0.2	mA	V _{CC} = 5.25 V, V _I = 0.4 V	
	I _I	—	—	0.1	mA	V _{CC} = 5.25 V, V _I = 7 V	
Short-circuit output current	I _{os}	-40	—	-225	mA	V _{CC} = 5.25 V	
Supply current**	Outputs high	I _{CC}	—	13	23	mA	V _{CC} = 5.25 V
	Outputs low		—	27	46		
	All outputs disabled		—	32	54		
Input clamp voltage	V _{IK}	—	—	-1.5	V	V _{CC} = 4.75 V, I _{IN} = -18 mA	

Notes: * V_{CC} = 5 V, Ta = 25°C

** I_{CC} is measured with all outputs open.

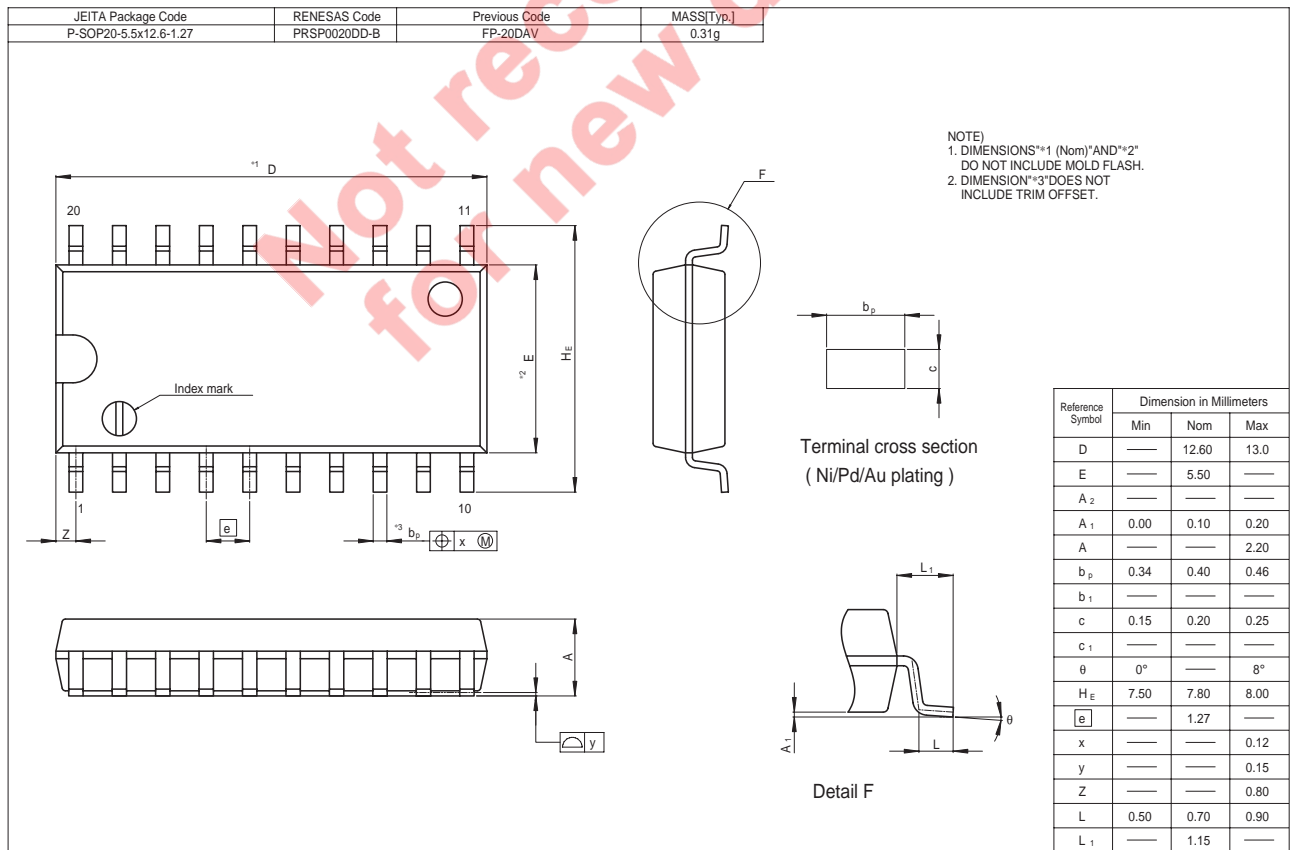
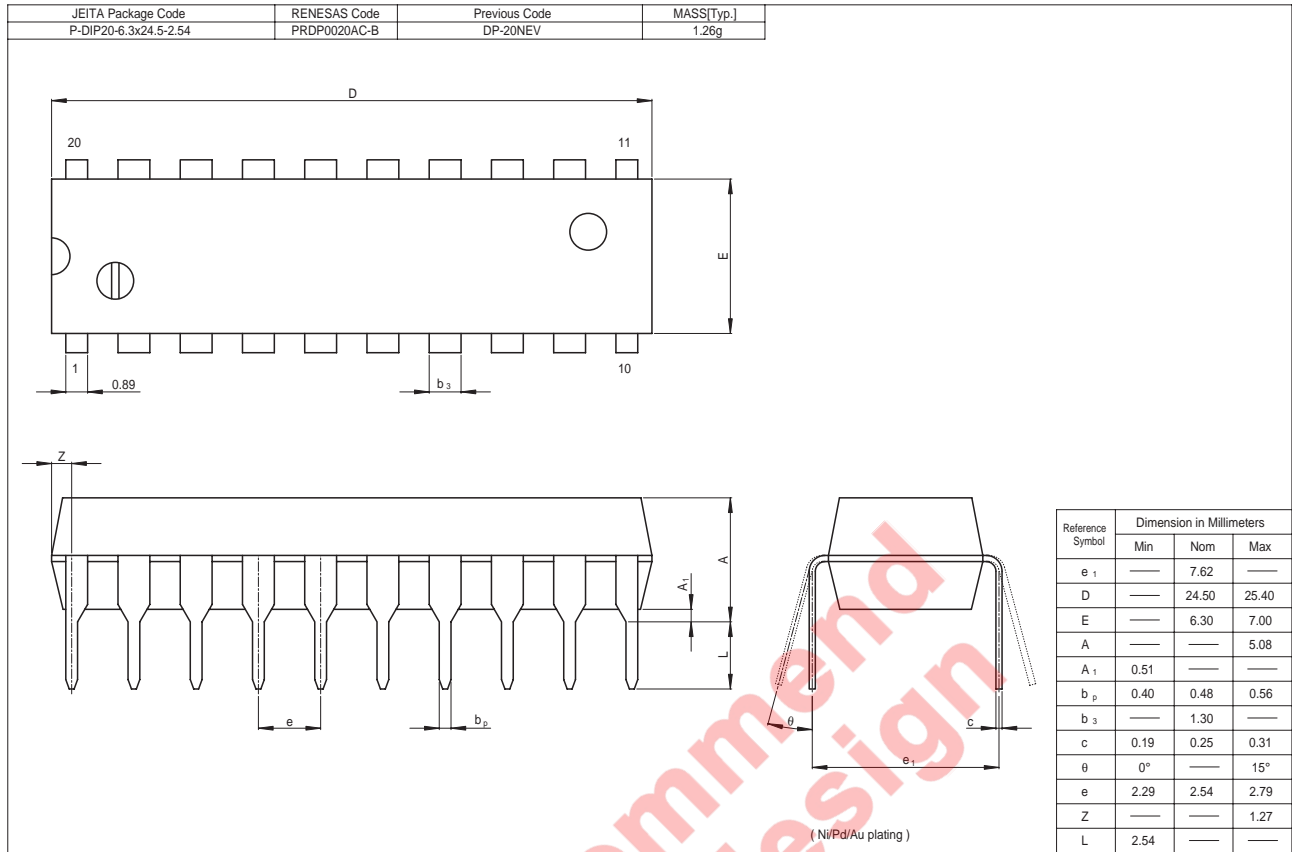
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t _{PLH}	—	12	18	ns	C _L = 45 pF, R _L = 667 Ω
	t _{PHL}	—	12	18		
Output enable time	t _{ZL}	—	20	30	ns	
	t _{ZH}	—	15	23	ns	
Output disable time	t _{LZ}	—	15	25	ns	C _L = 5 pF, R _L = 667 Ω
	t _{HZ}	—	10	18	ns	

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions



Renasantech Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs!

1. Renasantech Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renasantech Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renasantech Technology Corp. or a third party.
2. Renasantech Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renasantech Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renasantech Technology Corp. or an authorized Renasantech Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors.
Renasantech Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Renasantech Technology Corp. by various means, including the Renasantech Technology Corp. Semiconductor home page (<http://www.renesas.com>).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renasantech Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renasantech Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renasantech Technology Corp. or an authorized Renasantech Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renasantech Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renasantech Technology Corp. for further details on these materials or the products contained therein.



RENEASAS SALES OFFICES

<http://www.renesas.com>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

Renasantech Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renasantech Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renasantech Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renasantech Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renasantech Technology (Shanghai) Co., Ltd.
Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renasantech Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001